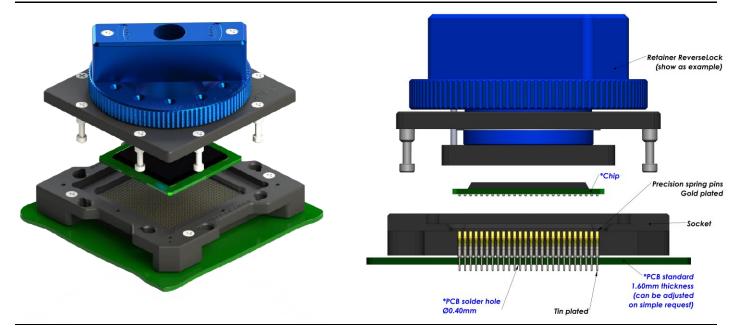
Through-hole (THT) soldering Test Socket

For BGA / Bumped chip / WLCSP / eMMC Package 0.80 mm pitch (from 0.80 mm up to 0.99 mm)





E-tec Interconnect AG is the world leading Test socket manufacturer

The Through-hole socket uses the same footprint as your chip. Socket is simply placed and wave soldered onto the PCB in the same way as the chip and it only requires a small amount of additional board space. Through-hole sockets are available with all retention systems. Please note, we will always request the chip data to ensure we offer a compatible socket.

Specifications contact type code 0870								
Application	Through-hole technology	Force	30 gr					
Mounting	THT	Current rating	1.8 A					
Bandwidth (GHz@-1dB)	3.4 GHz	Capacitance pF	0.59 pF					
Contact resistance	<100mOhm	Inductance nH	1.70 nH					
Chip contact tip shape	Single Point tip or Concave tip	Temperature range	-55°C to +150°C					
PCB tip shape	Through-hole	Mating cycles	100 K					

How to order

BU # #### -087# - ###### #5 #

Shape of tip	<u>Nbr of</u>	<u>Conta</u>	Contact type		Plating		Option code (see page 16-19)	
U:Concave	<u>contacts</u>	70 : Standard THT			95:Tin / Gold	D :	Dead bug	
Options:	Depends on ballcount of chip	72 : Special THT to pl	ug into MGS adapters		55:Gold / Go	ld M:	Multi frames	
P:Pointed	ballcount of chip						Multi packages	
S:Spring					Other on reque	est S :	Custom opening slot	
C : Crown						L :	Locating pegs	
						A :	Alignment plate	
Retention frame type (Lid) (see page 12-15)							Heatsink	
W: TwistLock		S: ScrewLock					Fan + Heatsink	
F : FastLock		Q: Open Quick	Lock (<200 contacts)				Thermal drain pad	
B:SpringLock		D: QuickLock (>200 contacts)				Transparent lid	
H: Open Clamshell Alu (<200 contacts)		M: Injection Molded ClamShell				1:	Steel retention lid	
J: Clamshell Alu (>200 contacts)		R: ReverseLock				B :	Aluminium retention lid	
L: Open Lever Clamshell Alu (>200 contacts)		T : SlimLock				T :	Torque tool fixture	
						G :	Handling button	

